



Material Content Data Sheet



Sales Product Name	TLE4254GS			Issued	20. July 2018			
MA#	MA001370040							
Package	PG-DSO-8-46			Weight*	82.94 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.779	2.14	2.14	21444	21444
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		436	
	non noble metal	iron	7439-89-6	0.723	0.87		8721	
wire	non noble metal	copper	7440-50-8	29.372	35.41	36.33	354120	363386
	non noble metal	copper	7440-50-8	0.087	0.10	0.10	1044	1044
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1177
encapsulation	plastics	epoxy resin	-	4.490	5.41		54135	
	inorganic material	silicondioxide	60676-86-0	44.217	53.34	58.87	533109	588421
leadfinish	non noble metal	tin	7440-31-5	0.824	0.99	0.99	9935	9935
plating	noble metal	silver	7440-22-4	0.144	0.17	0.17	1738	1738
glue	plastics	epoxy resin	-	0.291	0.35		3508	
	noble metal	silver	7440-22-4	0.873	1.05	1.40	10524	14032
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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